2/4/03

BY TELEFAX TO: (703) 872-9310

DOCKET NO.: 4029

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN THE MATTER OF THE APPLICATION FOR PATENT

OF: Michio OSADA et al.

| Art Unit: 1722

SERIAL NO.: 09/705,237

| Confirmation No.: 4586

FILED: November 2, 2000

EX.: Thukhanh T. Nguyen

FOR: Die Used for Resin-Sealing and

Molding an Electronic Component

ASSISTANT COMMISSIONER FOR PATENTS BOX RESPONSE - NO FEE

WASHINGTON, D.C. 20231

January 31, 2003

RESPONSE TO THE OFFICE ACTION OF OCTOBER 31, 2002 INCLUDING AN ATTACHED COVER SHEET WITH CERTIFICATE OF TELEFAX TRANSMISSION

Dear Sir:

Please amend the above identified application as follows.

In the Specification:

Please delete and replace the paragraph at page 4, lines 16 to 19, to read as follows:

Furthermore, if coating layer (A) has a tungsten content of approximately 10% by weight then electrolysis rapidly increases the layer's electrostatic stress and also decreases the layer's flexibility. This results in a crack in a surface of the coating layer.

4029/WFF:ar

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